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CONFIRMATION NO. 8507

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## FILING RECEIPT



\*OC000000011452873\*

Date Mailed: 12/10/2003

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

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## Assignment For Published Patent Application

Endicott Interconnect Technologies, Inc., Endicott, NY;

## Domestic Priority data as claimed by applicant

This application is a CIP of 10/394,107 03/24/2003  
which is a CIP of 10/354,000 01/30/2003

## Foreign Applications

If Required, Foreign Filing License Granted: 12/05/2003

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Early Publication Request: No

Title



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☒ Application ☐ Issue Fee  
☒ Declaration 2 pgs. ☐ Draftsman w/Dwgs.  
x signed        unsigned ☒ Cert. Of Mailing  
☒ Assignment w/Cover Pg. ☐  
☒ IDS/PTO-1449/Refs.  
☐ Amendment  
Title Stacked Chip Electronic Package Having Laminate  
Carrier And Method Of Making Same  
31 Pgs. Spec. 24 Claims 12 Shts. Of Drawing  
\$822.00 Filing Fee Attorney Lawrence R. Fraley  
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